

US Department of Commerce Patent and Trademark Office Form PTO-1449 (Modified)	Atty. Docket No.: 42390P5593C	Application No.: * * * * *
	Applicant: Chia-Pin Chiu	
	Filing Date: Concurrently Herewith	

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US Patent Documents

Examiner's Initials	Date	Document Number	Name	Class	Sub- Class	Filing Date
AS	10/21/97	5,679,457	Bergerson			03/18/96
AS	06/01/93	5,216,283	Lin			05/03/90
AS	04/10/90	4,915,167	Altoz			08/05/98
AS	04/28/98	5,745,344	Baska et al			11/06/95

Foreign Patent Documents

Examiner's Initials	Date	Document Number	Country	Class	Sub- Class	Translation

Other Documents (Including Author, Title, Date, Pertinent Pages, etc.)

AS	Heat Transfer Fundamentals. Whitepaper [online] [Retrieved on June 27, 2000] Retrieved from the Internet: <URL:http://www.chomerics.com/heattransferfund.html. Pages 1-7.
AS	Kent Young, Thermal Gap Fillers: New Material Overcomes Performance Trade-Offs. Chomerics, Marlow, Buckinghamshire, UK. Pages 1-2.
AS	THERMFLOW™ Low Thermal Resistance Phase-Change Interface Pads. [online] Product Data Sheet. [Retrieved on 10/25/2001] Retrieved from the Internet: <URL:http://www.chomerics.com/products/documents/TB77page.pdf. Pages 1-2.

Examiner <i>Flanigan</i>	Date Considered <i>2/28/05</i>
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Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw a line through the citation if not in conformance and not considered. Include a copy of this form with the next communication to the applicant